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ABSTRACT

A semiconductor device comprising: a substrate (30) including a plurality of holes (36) and a surface over which an interconnecting pattern (32) is formed, part of the interconnecting pattern (32) being superposed over the holes (36); a semiconductor chip (10) including a plurality of electrodes (12) which are disposed over another surface of the substrate (30) to correspond to the holes (36); and conductive members provided within the holes (36) for electrically connecting the electrodes (12) to the interconnecting pattern (32).